



Chris Butterfield  
ESI  
503-672-5760

**FOR RELEASE**

## **NEW ASIAN CUSTOMER ADOPTS ESI's INNOVATIVE DUAL-BEAM IR LASER SYSTEM, THE MODEL 9850**

*Order Signals Another Competitive Win for ESI in the Korean Market*

**PORTLAND, Ore.—Sept. 12, 2007**— Electro Scientific Industries, Inc. (Nasdaq: ESIO), a leading provider of world-class photonic and laser systems for micro-engineering applications, received an order for the Model 9850 dual-beam infrared (IR) laser link-processing system from a new customer in Korea. Featuring an innovative architecture that utilizes two beams from a single laser to enable the industry's first parallel processing capability, the Model 9850 enables potential throughput improvements of up to 90 percent when compared with conventional laser repair systems. This new customer will utilize ESI's Model 9850 system for volume production of DRAM and NAND Flash memory devices. ESI plans to ship the Model 9850 IR link-processing system this month.

ESI developed its unique laser architecture to meet the increasing demand and ramp for leading-edge DRAM and NAND Flash memory devices. The 9850 dual-beam laser system leverages the company's state-of-the-art IR dual beam laser technology, so that customers can realize the highest precision, reliability and cost-of-ownership advantages.

"This order is another example of how ESI is delivering innovative solutions that support next-generation, high-end memory production requirements," noted Paul Kirby, semiconductor link processing product marketing manager. "The 9850IR system will be used to improve the yield of our customer's advanced memory devices by substituting redundant memory cells for defective cells on each chip. We welcome this new customer to the ESI family and reinforce our commitment to continue to deliver solutions with leading technology and low-cost advantages to improve our customers' competitive edge."

## **ESI Model 9850 Features**

The Model 9850 is the world's first multiple-beam delivery laser repair system. The system's innovative architecture processes tight-pitch metal fuses on the latest generation of DRAM and NAND Flash devices. The 9850 was designed for high-throughput, automated, 300-mm production environments and enables whole-wafer processing with half the number of link runs. The system improves cost-of-ownership by providing more productivity with no increase in maintenance or floor space requirements. In addition, the system software automatically optimizes dual-beam processing for the maximum throughput advantage on a wide range of products.

## **About ESI, Inc.**

ESI is a pioneer and leading supplier of world-class photonic micro-engineering solutions that help its microelectronics customers achieve compelling yield and productivity gains. The company's industry-leading, application-specific products enhance electronic-device performance in three key sectors—semiconductors, components and electronic interconnect—by enabling precision fine-tuning of device microfeatures in high-volume manufacturing environments. Founded in 1944, ESI is headquartered in Portland, Ore. More information is available at [www.esi.com](http://www.esi.com).

## **Forward-Looking Statements**

*This press release includes forward-looking statements concerning the timing of systems shipments. Actual results may differ materially from those in the forward-looking statements. Risks and uncertainties that may affect the forward-looking statements include: the relative strength and volatility of the electronics industry -- which is dependent on many factors including component prices, global economic strength and political stability, and overall demand for electronic devices (such as capacitors) used in computers, flat panel displays, automotive applications, and video games; the risk that customer orders may be canceled or delayed; and the risk of manufacturing, supply or shipment disruptions or delays.*

###